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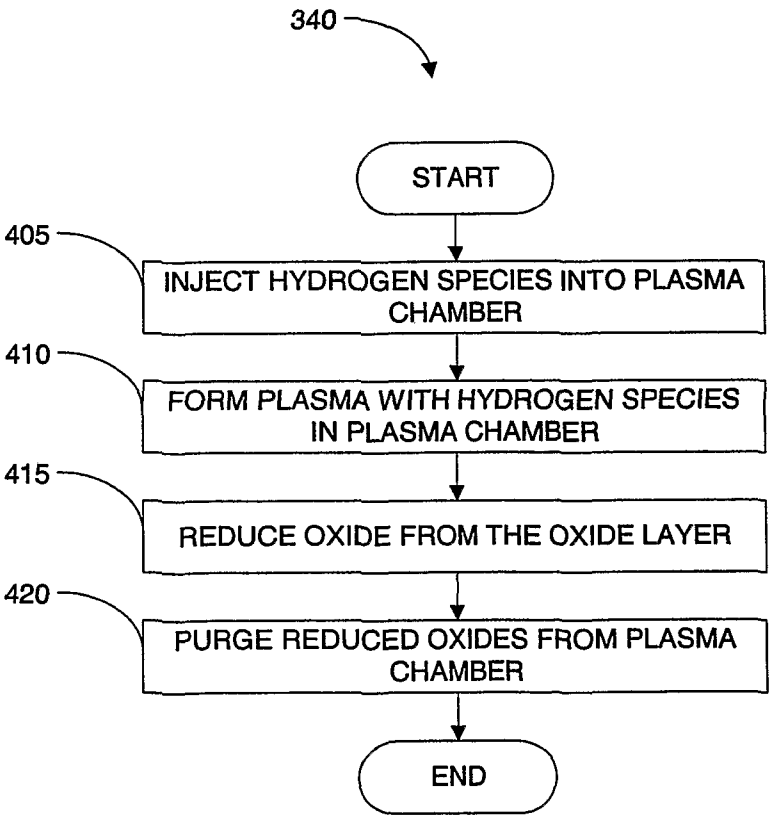
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(54) Title: SYSTEM AND METHOD FOR SURFACE REDUCTION, PASSIVATION, CORROSION PREVENTION AND ACTIVATION OF COPPER SURFACE



(57) Abstract: A system and method of passivating an exposed conductive material includes placing a substrate in a process chamber and injecting a hydrogen species into the process chamber. A hydrogen species plasma is formed in the process chamber. A surface layer species is reduced from a top surface of the substrate is reduced. The reduced surface layer species are purged from the process chamber.

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